

GENE-BT04

Thermal Image Analysis Report

Report NO: 15E090037

Test Cause

For ATRF No.QE150916 Request

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: <u>There are 3 temperature points marginal passed, the functions are normal,</u>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	3
Defect Unsolved	0	0	0	3

Issue date

2015 / 10 / 07

Approval

KJ Wang

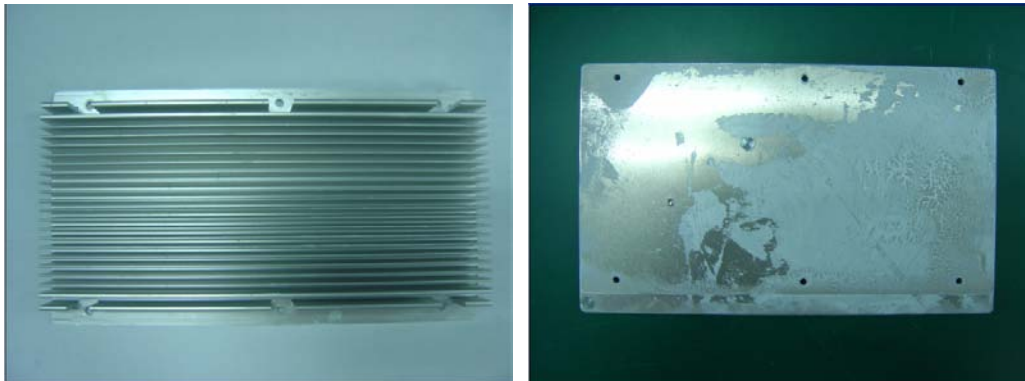
Test Engineer

JunoCheng

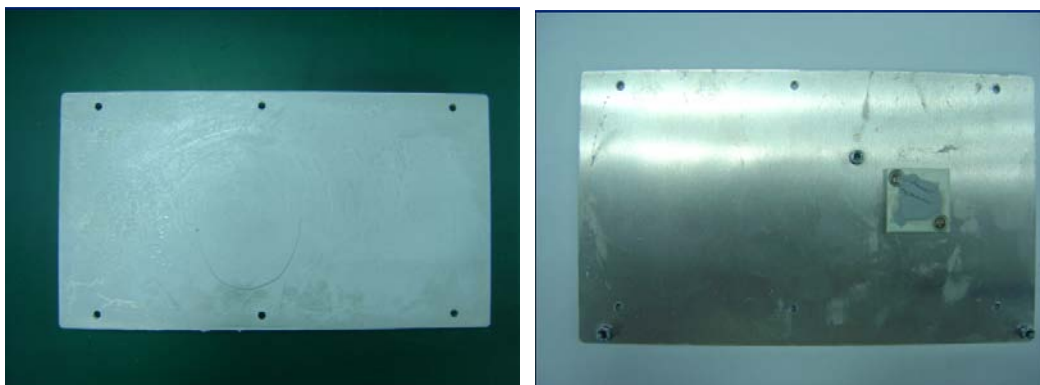
Sample Configuration & Quantity Under Test

- Model name : GENE-BT04 A1.0
- CPU : Intel J1900 1.99GHz
- Memory : Innodisk DDR3L-1600 SODIMM/ K4B4G084G0/8GB
- CFast : Innodisk 32GB 3ME
- BIOS : GENE-BT04 R1.0 (GBT4AM10) (07/01/2015)
- Test Software : Windows 7 / Run BurnIn test 8.0 Pro
- Power : AT Power
- Heat Sink with Fan & Heat spreader:

Heat Sink (P/N): M16BT06000



Heat spreader(P/N): M10BT04010



Thermal Image Analysis

1. Test Date: 2015-10-07

2. Test Product: GENE-BT04

3. Test Site: AAEON QE Dept.

4. Temperature Measurement:

4.1. 40 Channel Thermal Recorder:

4.1.1 YOKOGAWA Inc,

4.2.2 Model: DA100-13-1D

Date of Calibration: 2015/09/10

Serial Number: 12A323190

4.2. IR Scanner: Infrared Camera

4.2.1 NEC Avio Infrared Technologies Co., Ltd.

4.2.2 Model: Thermo GEAR G100W2-D

Date of Calibration: 2014/12/30

Serial Number: 1051444

5. Test Condition:

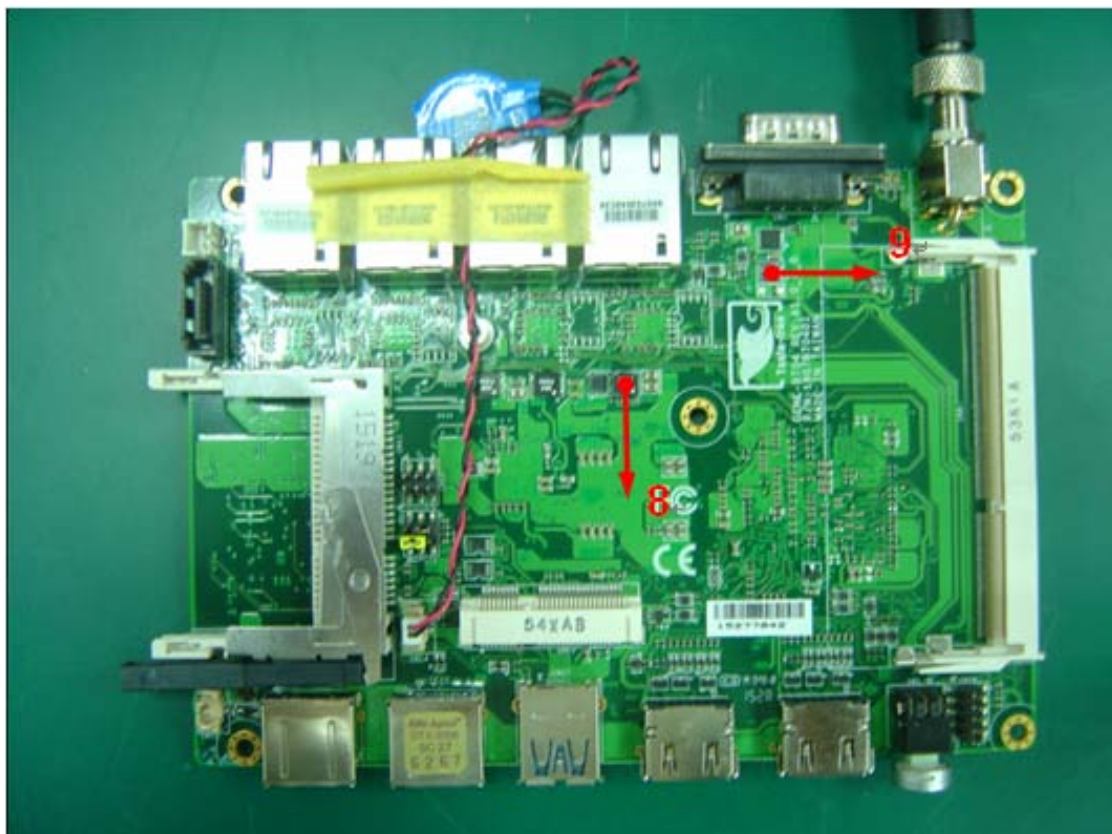
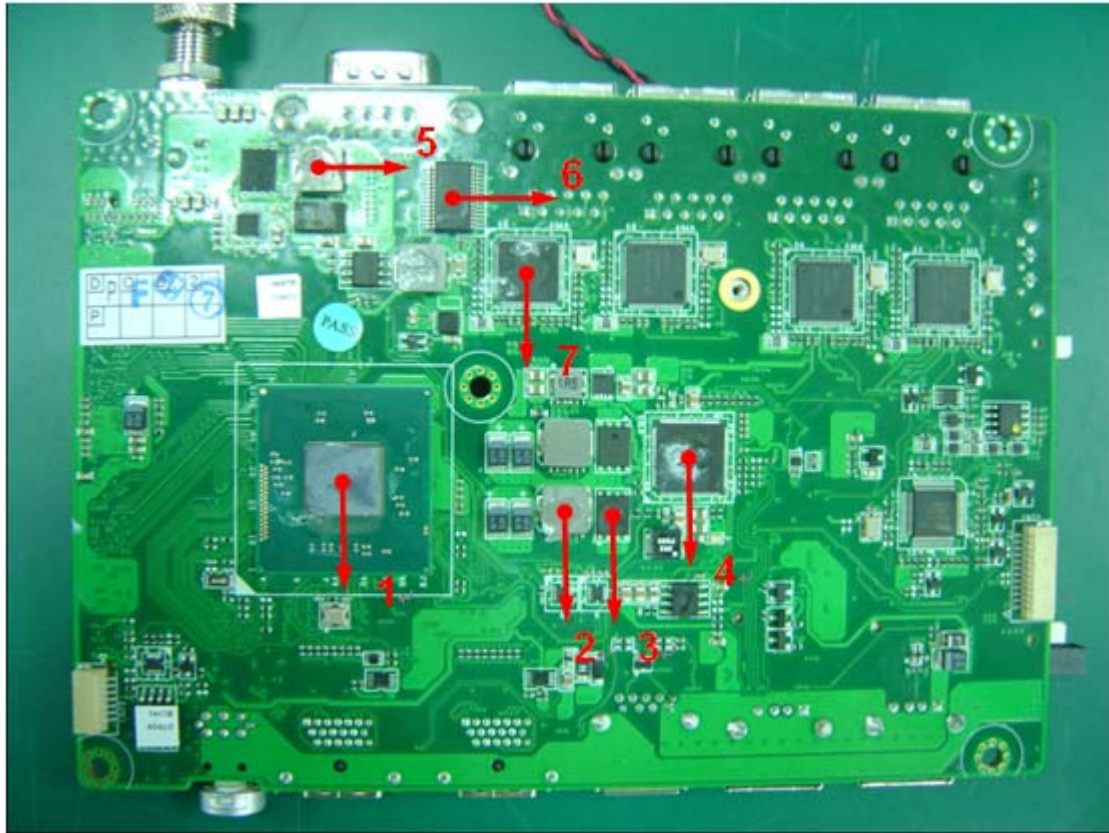
Test by DA-100: 24.8°C with HeatSink

6. Take Picture Time:

After power on 2 hours

Terminal Recorder:

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2)	Note
				Measured Under 60°C	
1	U29	Intel® Celeron® Processor J1900	105	84.7	
2	L8	(TF)COIL.0.33uH.ZenithTek.ZPWM-6030M-R33M	150	79.1	
3	Q33	(TF)PWR.DUALSMD.N-MOSFET.PQFN8.FAIRCHILD.FDMS3664S	125	81.9	
4	U27	(TF)IC.PMIC.for Intel Valleyview.ROHM.BD9596MWV	125	82.2	
5	L1	(TF)COIL.1uH.DCR=6.7mohm.Idc=14Amp.20%.SMD.7.3*6.8*3mm.HDTPower.MPC-7066CZ-1R0-M	150	91.2	
6	U17	(TF)IC.RS232 Driver/Receiver.15KV ESD.SSOP28P.SMD.TI.TRS213IDBR	125	78.6	
7	U23	(TF)IC.PCI-E GigaBit Ethernet Chipset.QFN64P.SMD.Intel.WGI211AT	85	80.7	NOTE3
8	L3	(TF)COIL.1uH.DCR=24mohm.Idc=4.5Amp.20%.SMD.4.45*4.05*2.0mm.Zenithtek.ZPWM-4020M-1R0M	150	78.6	
9	Q5	(TF)PWR.SMD.MLP MOSFET.FAIRCHILD.FDMC4435BZ	125	80.6	
10		DIMM	85	83.4	NOTE3
11		CFast	85	76.0	NOTE3

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
- **Margin** : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.

- RTC battery avoid to put on heat position. Please do not exceed battery temperature specification.